

# 3.3V CMOS 12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCH WITH 3-STATE OUTPUTS AND BUS-HOLD

# IDT74ALVCH16260

## FEATURES:

- 0.5 MICRON CMOS Technology
- Typical tSK(o) (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- Vcc = 3.3V ± 0.3V, Normal Range
- Vcc = 2.7V to 3.6V, Extended Range
- Vcc = 2.5V ± 0.2V
- CMOS power levels (0.4µ W typ. static)
- · Rail-to-Rail output swing for increased noise margin
- Available in TSSOP package

## **DRIVE FEATURES:**

- High Output Drivers: ±24mA
- · Suitable for heavy loads

## **APPLICATIONS:**

- 3.3V high speed systems
- 3.3V and lower voltage computing systems

# **DESCRIPTION:**

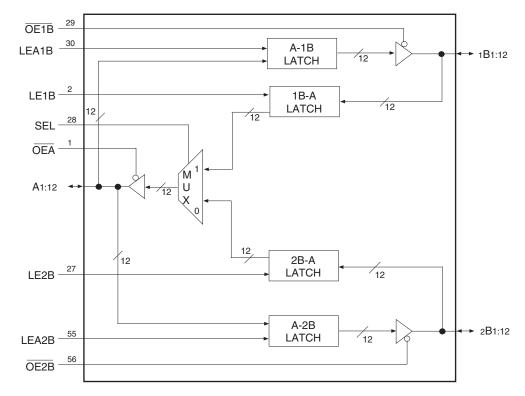
This 12-bit to 24-bit multiplexed D-type latch is built using advanced dual metal CMOS technology. The ALVCH16260 is used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. Typical applications include multiplexing and/or demultiplexing address and data information in microprocessor or bus-interface applications. This device also is useful in memory interleaving applications.

Three 12-bit I/O ports (A1-A12, 1B1-1B12, and 2B1-2B12) are available for address and/or data transfer. The output-enable (OE1B, OE2B, and OEA) inputs control the bus transceiver functions. The OE1B and OE2B control signals also allow bank control in the A-to-B direction. Address and/or data information can be stored using the internal storage latches. The latch-enable (LE1B, LE2B, LEA1B, and LEA2B) inputs are used to control data storage. When the latch-enable input is high, the latch is transparent. When the latchenable input goes low, the data present at the inputs is latched and remains latched until the latch-enable input is returned high.

The ALVCH16260 has been designed with a  $\pm$ 24mA output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

The ALVCH16260 has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.





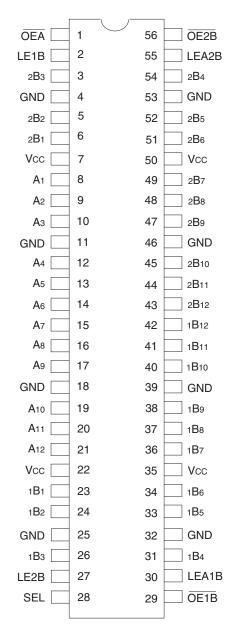
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### INDUSTRIAL TEMPERATURE RANGE

**JULY 2009** 

#### 3.3V CMOS 12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCH

### **PIN CONFIGURATION**



TSSOP TOP VIEW

#### **INDUSTRIAL TEMPERATURE RANG**

# ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Description	Max	Unit
VTERM <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
VTERM <sup>(3)</sup>	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
TSTG	Storage Temperature	-65 to +150	°C
Ιουτ	DC Output Current	-50 to +50	mA
lıк	Continuous Clamp Current, VI < 0 or VI > Vcc	±50	mA
Іок	Continuous Clamp Current, Vo < 0	50	mA
ICC ISS	Continuous Current through each Vcc or GND	±100	mA

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. Vcc terminals.

3. All terminals except Vcc.

### CAPACITANCE (TA = +25°C, F = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	5	7	pF
Соит	Output Capacitance	Vout = 0V	7	9	pF
CI/O	I/O Port Capacitance	VIN = 0V	7	9	pF

NOTE:

1. As applicable to the device type.

### **FUNCTION TABLES(1)**

### B-TO-A ( $\overline{OEB} = H$ )

	Output					
1Bx	2Bx	SEL	LE1B	LE2B	ŌĒĀ	Ax
Н	Х	Н	Н	Х	L	Н
L	Х	Н	Н	Х	L	L
Х	Х	Н	L	Х	L	A <sub>0</sub> <sup>(2)</sup>
Х	Н	L	Х	Н	L	Н
Х	L	L	Х	Н	L	L
Х	Х	L	Х	L	L	A <sub>0</sub> <sup>(2)</sup>
Х	Х	Х	Х	Х	Н	Z

#### **NDUSTRIAL TEMPERATURE RANGE**

# FUNCTION TABLES (CONTINUED)(1)

A-10-D (UEA = H)									
		Outp	outs						
Ax	LEA1B	LEA2B	OE1B	OE2B	1Bx	2Bx			
Н	Н	Н	L	L	Н	Н			
L	Н	Н	L	L	L	L			
Н	Н	L	L	L	Н	2B <sub>0</sub> <sup>(2)</sup>			
L	Н	L	L	L	L	2B <sub>0</sub> <sup>(2)</sup>			
Н	L	Н	L	L	1B <sub>0</sub> <sup>(2)</sup>	Н			
L	L	Н	L	L	1B <sub>0</sub> <sup>(2)</sup>	L			
Х	L	L	L	L	1B <sub>0</sub> <sup>(2)</sup>	2B <sub>0</sub> <sup>(2)</sup>			
Х	Х	Х	Н	Н	Z	Z			
Х	Х	Х	L	Н	Active	Z			
Х	Х	Х	Н	L	Z	Active			
Х	Х	Х	L	L	Active	Active			

А-ТО-В (<u>ОЕА</u> = Н)

#### NOTES:

1. H = HIGH Voltage Level

L = LOW Voltage Level

X = Don't Care

Z = High Impedance

2. Output level before the indicated steady-state input conditions were established.

## **PIN DESCRIPTION**

Pin Names	I/O	Description
Ax(1:12)	I/O	Bidirectional Data Port A. Usually connected to the CPU's address/data bus. <sup>(1)</sup>
1Bx(1:12)	I/O	Bidirectional Data Port 1B. Usually connected to the even path or even bank of memory. <sup>(1)</sup>
2Bx(1:12)	I/O	Bidirectional Data Port 2B. Usually connected to the odd path or odd bank of memory. <sup>(1)</sup>
LEA1B	I	Latch Enable Input for A-1B Latch. The latch is open when LEA1B is HIGH. Data from the A-port is latched on the HIGH to LOW transition of LEA1B.
LEA2B	I	Latch Enable Input for A-2B Latch. The latch is open when LEA2B is HIGH. Data from the A-port is latched on the HIGH to LOW transition of LEA2B.
LE1B	I	Latch Enable Input for 1B-A Latch. The latch is open when LE1B is HIGH. Data from the A-port is latched on the HIGH to LOW transition of LE1B.
LE2B	I	Latch Enable Input for 2B-A Latch. The latch is open when LE2B is HIGH. Data from the A-port is latched on the HIGH to LOW transition of LE2B.
SEL	I	1B or 2B Port Selection. When HIGH, SEL enables data transfer from 1B Port to A Port. When LOW, SEL enables data transfer from 2B Port to A Port.
ŌĒĀ	I	Output Enable for A Port (Active LOW)
OE1B	I	Output Enable for 1B Port (Active LOW)
OE2B	I	Output Enable for 2B Port (Active LOW)

NOTE:

1. These pins have "Bus-Hold". All other pins are standard inputs, outputs, or I/Os.

# DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified: Operating Condition: TA =  $-40^{\circ}$ C to  $+85^{\circ}$ C

Symbol	Parameter	Test C	onditions	Min.	Typ. <sup>(1)</sup>	Max.	Unit
Vih	Input HIGH Voltage Level	Vcc = 2.3V to 2.7V		1.7	—	—	V
		Vcc = 2.7V to 3.6V		2	-	_	
VIL	Input LOW Voltage Level	Vcc = 2.3V to 2.7V			-	0.7	V
		Vcc = 2.7V to 3.6V		—	—	0.8	
Ін	Input HIGH Current	Vcc = 3.6V	VI = VCC	—	—	±5	μA
lı∟	Input LOW Current	Vcc = 3.6V	VI = GND	-	—	±5	μA
lozн	High Impedance Output Current	Vcc = 3.6V	Vo = Vcc	_	—	±10	μA
Iozl	(3-State Output pins)		Vo = GND	_	_	±10	
Vik	Clamp Diode Voltage	Vcc = 2.3V, IIN = -18mA			-0.7	-1.2	V
νн	Input Hysteresis	Vcc = 3.3V			100	_	mV
ICCL ICCH ICCZ	Quiescent Power Supply Current	Vcc = 3.6V VIN = GND or Vcc		-	0.1	40	μA
AICC	Quiescent Power Supply Current Variation	One input at Vcc - 0.6V, other	r inputs at Vcc or GND	-	—	750	μA

NOTE:

1. Typical values are at Vcc = 3.3V, +25°C ambient.

## **BUS-HOLD CHARACTERISTICS**

Symbol	Parameter <sup>(1)</sup>	Test Conditions		Min.	Typ. <sup>(2)</sup>	Max.	Unit
Івнн	Bus-Hold Input Sustain Current	Vcc = 3V	VI = 2V	-75	_	_	μA
IBHL			VI = 0.8V	75	-		
Івнн	Bus-Hold Input Sustain Current	Vcc = 2.3V	VI = 1.7V	-45	_	_	μA
IBHL			VI = 0.7V	45	—	—	
Івнно	Bus-Hold Input Overdrive Current	VCC = 3.6V	VI = 0 to 3.6V	—	—	±500	μA
Ibhlo							

NOTES:

1. Pins with Bus-Hold are identified in the pin description.

2. Typical values are at Vcc = 3.3V, +25°C ambient.

# **OUTPUT DRIVE CHARACTERISTICS**

Symbol	Parameter	Test Con	Min.	Max.	Unit	
Vон	Output HIGH Voltage	Vcc = 2.3V to 3.6V	Iон = - 0.1mA	Vcc-0.2	—	V
		Vcc = 2.3V	Iон = - 6mA	2	_	
		Vcc = 2.3V	Iон = - 12mA	1.7		
		Vcc = 2.7V		2.2	_	
		Vcc = 3V		2.4	—	
		Vcc = 3V	Iон = - 24mA	2	—	
Vol	Output LOW Voltage	Vcc = 2.3V to 3.6V	IOL = 0.1mA	—	0.2	V
		Vcc = 2.3V	IOL = 6mA	—	0.4	
			IOL = 12mA	—	0.7	
		Vcc = 2.7V	IoL = 12mA	_	0.4	
		Vcc = 3V	Iol = 24mA	_	0.55	

#### NOTE:

1. VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate Vcc range. TA = − 40°C to + 85°C.

# **OPERATING CHARACTERISTICS, TA = 25°C**

			$Vcc = 2.5V \pm 0.2V$	$Vcc = 3.3V \pm 0.3V$	
Symbol	Parameter	Test Conditions	Typical	Typical	Unit
Cpd	Power Dissipation Capacitance Outputs enabled	CL = 0pF. f = 10Mhz	37	41	pF
Cpd	Power Dissipation Capacitance Outputs disabled		4	7	

## SWITCHING CHARACTERISTICS(1)

		$Vcc = 2.5V \pm 0.2V$		Vcc	= 2.7V	Vcc = 3.3	3V ± 0.3V		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit	
tPLH	Propagation Delay	1	5.4	—	5.1	1.2	4.3	ns	
<b>t</b> PHL	Ax to 1Bx or Ax to 2Bx								
tPLH	Propagation Delay	1	5.4	-	5.1	1.2	4.3	ns	
<b>t</b> PHL	1Bx to Ax or 2Bx to Ax								
tPLH	Propagation Delay	1	5.6	-	5.2	1	4.4	ns	
<b>t</b> PHL	LEXB to Ax								
tPLH	Propagation Delay	1	5.6	-	5.2	1	4.4	ns	
<b>t</b> PHL	LE1B to 1BX or LEA2B to 2Bx								
tPLH	Propagation Delay	1	6.9	-	6.6	1.1	5.6	ns	
<b>t</b> PHL	SEL to Ax								
tPZH	Output Enable Time	1	6.7	-	6.4	1	5.4	ns	
tPZL	$\overline{\text{OEA}}$ to Ax, $\overline{\text{OE1B}}$ to 1Bx, or $\overline{\text{OE2B}}$ to 2Bx								
tPHZ	Output Disable Time	1	5.7	-	5	1.3	4.6	ns	
tPLZ	$\overline{\text{OEA}}$ to Ax, $\overline{\text{OE1B}}$ to 1Bx, or $\overline{\text{OE2B}}$ to 2Bx								
ts∪	Set-up Time, data before LE1B, LE2B, LEA1B, LEA2B	1.4	-	1.1	-	1.1	-	ns	
tΗ	Hold Time, data after LE1B, LE2B, LEA1B, LEA2B	1.6	_	1.9	_	1.5	-	ns	
tw	Pulse Width, LE1B, LE2B, LEA1B, or LEA2B HIGH	3.3	-	3.3	_	3.3	-	ns	
tsk(0)	Output Skew <sup>(2)</sup>	-	-	_	_	-	500	ps	

#### NOTES:

1. See TEST CIRCUITS AND WAVEFORMS. TA = -  $40^{\circ}$ C to +  $85^{\circ}$ C.

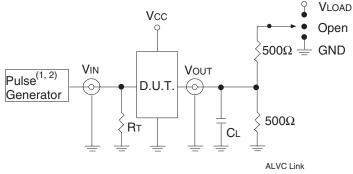
2. Skew between any two outputs of the same package and switching in the same direction.

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#### INDUSTRIALTEMPERATURERANG

# TEST CIRCUITS AND WAVEFORMS TEST CONDITIONS

Symbol	Vcc <sup>(1)</sup> =3.3V±0.3V	Vcc <sup>(1)</sup> =2.7V	Vcc <sup>(2)</sup> =2.5V±0.2V	Unit
VLOAD	6	6	2 x Vcc	V
Vih	2.7	2.7	Vcc	V
Vт	1.5	1.5	Vcc / 2	V
Vlz	300	300	150	mV
Vнz	300	300	150	mV
CL	50	50	30	pF



Test Circuit for All Outputs

### **DEFINITIONS:**

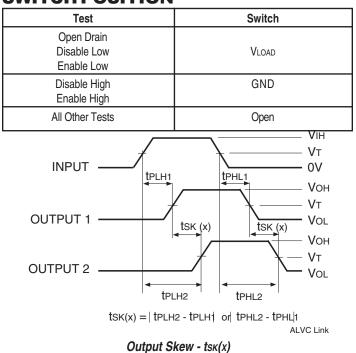
CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.

#### NOTES:

1. Pulse Generator for All Pulses: Rate  $\leq$  1.0MHz; tF  $\leq$  2.5ns; tR  $\leq$  2.5ns. 2. Pulse Generator for All Pulses: Rate  $\leq$  1.0MHz; tF  $\leq$  2ns; tR  $\leq$  2ns.

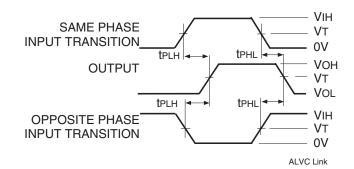
### **SWITCH POSITION**



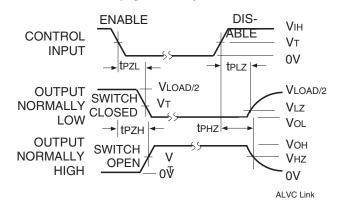


1. For tsk(o) OUTPUT1 and OUTPUT2 are any two outputs.

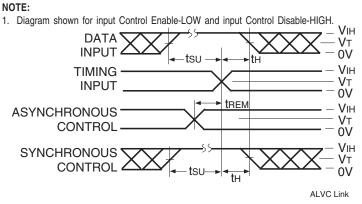
2. For tsk(b) OUTPUT1 and OUTPUT2 are in the same bank.



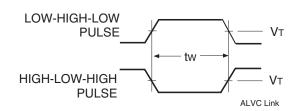
### **Propagation Delay**



### Enable and Disable Times

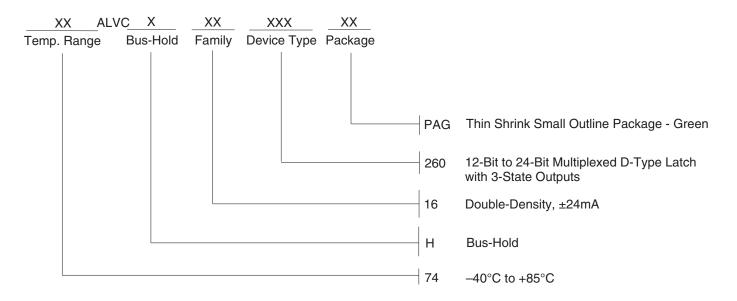


### Set-up, Hold, and Release Times



Pulse Width

## **ORDERING INFORMATION**





**CORPORATE HEADQUARTERS** 6024 Silver Creek Valley Road San Jose, CA 95138 for SALES: 800-345-7015 or 408-284-8200 fax: 408-284-2775 www.idt.com for Tech Support: logichelp@idt.com